

08-03-1999

RECORDATION

Atty. Docket: 35.G2444

To the Commissioner

attached original documents or copy thereof.



101107433

1. Name of conveying parties:

TAKAYUKI TESHIMA and TAKAYUKI YAGI

Additional names of conveying parties attached?

Yes No

Handwritten: MEX 7/27/99

3. Nature of conveyance:

Assignment Merger
 Security Agreement Change of Name
 Other

Execution Date: July 21, 1999

Name and address of receiving party:

Name: CANON KABUSHIKI KAISHA

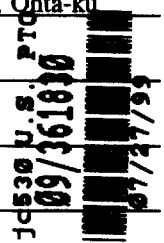
Foreign Address: 30-2, Shimomaruko 3-chome, Ohta-ku

Tokyo, Japan

Domestic Address:

City: State ZIP

Additional names & addresses attached? Yes No



4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: July 21, 1999

A. Patent Application Number: Not Yet Assigned

Attorney Dkt. No.: 35.G2444

B. Title of Invention:

SEMISPHERICAL MICROSTRUCTURE,
MICROLENS AND METHOD OF FABRICATING
THE SAME

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Fitzpatrick, Cella, Harper & Scinto

30 Rockefeller Plaza

New York, New York 10112-3801

Telephone No.: (212) 218-2100

Facsimile No.: (212) 218-2200

6. Number of applications and patents involved:

One

7. Total fee (37 CFR 3.41): . . . \$ 40.00

Enclosed
 Authorized to be charged to deposit account

8. Deposit account number (for deficiency or excess)

06-1205

(Attach duplicate copy of this page if paying by deposit account):

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and the attached is the original document or is a true copy of the original document.

Peter Saxon

Name of Person Signing

Signature

July 26, 1999

Date

Total number of pages including cover sheet, attachments, and documents: 2

JOINT
(BEFORE APPLICATION FILED)

ASSIGNMENT OF PATENT RIGHTS FOR THE UNITED STATES

FOR VALUE RECEIVED, WE, Takayuki Teshima and Takayuki Yagi

citizens of Japan

residing, respectively, at 2-10-1, Asahi-cho, Atsugi-shi, Kanagawa-ken, Japan;
1-15-16, Morigaoka, Isogo-ku, Yokohama-shi,
Kanagawa-ken, Japan

hereby sell, assign, transfer and convey unto Canon Kabushiki Kaisha

a corporation of Japan

having a place of business at 30-2, Shimomaruko 3-chome, Ohta-ku, Tokyo, Japan

its successors, assigns and legal representatives (hereinafter called the "Assignee"), the entire right, title and interest, for the United States, in and to certain inventions relating to
SEMISPHERICAL MICROSTRUCTURE, MICROLENS AND METHOD OF FABRICATING THE
SAME

and described in an application for Letters Patent of the United States executed by each of us, respectively, on the date indicated below and in and to said application, and all divisions, renewals and continuations thereof, and all Letters Patent of the United States which may be granted, thereon, and all reissues and extensions thereof; and we hereby authorize and request the Commissioner for Patents and Trademarks of the United States to issue all Letters Patent upon said inventions to the Assignee or to such nominees as it may designate.

AND we authorize and empower the said Assignee or nominees to invoke and claim for any application for patent or other form of protection for said inventions, the benefit of the right of priority provided by the International Convention for the Protection of Industrial Property, as amended, or by any convention which may henceforth be substituted for it, and to invoke and claim such right of priority without further written or oral authorization from us.

AND we hereby consent that a copy of this assignment shall be deemed a full legal and formal equivalent of any assignment, consent to file or like document which may be required in the United States for any purpose and more particularly in proof of the right of said Assignee or nominees to claim the aforesaid benefit of the right of priority provided by the International Convention for the Protection of Industrial Property, as amended, or by any convention which may henceforth be substituted for it.

AND we hereby covenant that we have the full right to convey the entire right, title and interest herein assigned and that we have not executed and will not execute any agreement in conflict herewith.

AND we hereby covenant and agree that we will communicate to said Assignee or nominees all facts known to us pertaining to said inventions, and testify in all legal proceedings, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and declarations and in general perform all lawful acts necessary or proper to aid said Assignee or nominees in obtaining, maintaining and enforcing all lawful patent protection for said inventions in the United States.

By: Takayuki Teshima
Takayuki Teshima

Date: July 21, 1999

By: Takayuki Yagi
Takayuki Yagi

Date: July 21, 1999